

ICS 31.080
CCS L 40



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 4937.2-2006

Replacing GB/T 4937-1995 Partial

**Semiconductor devices -- Mechanical and climatic test methods
-- Part 2: Low air pressure**

半导体器件 机械和气候试验方法 第2部分：低气压

(English Translation)

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What this standard covers

This standard applies to low pressure testing of semiconductor devices. The purpose of this test is a side fixed components and material ability to prevent electrical breakdown failure, and this failure is due to air pressure decreases, the air insulation and other insulating material weakening caused. This item applies only to face trial work voltage exceeding 1 000 V devices. This test applies to all air sealing semiconductor devices. This test applies only to military and space fields. The term low pressure test methods and IEC 60068-2-13 largely the same, but in view of the special requirements of semiconductor devices, the use of this part of the terms.

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Standards quoted by this document

IEC 60068-2-13